

MECHANICAL CASE OUTLINE PACKAGE DIMENSIONS

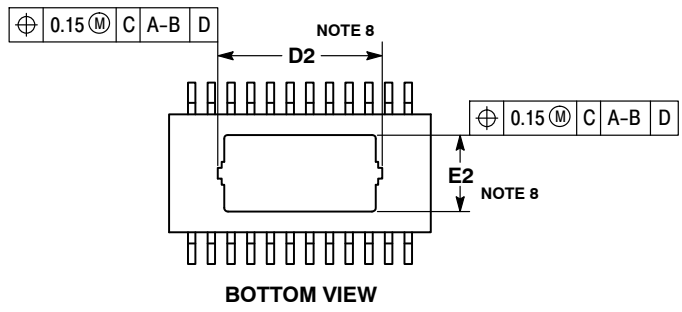
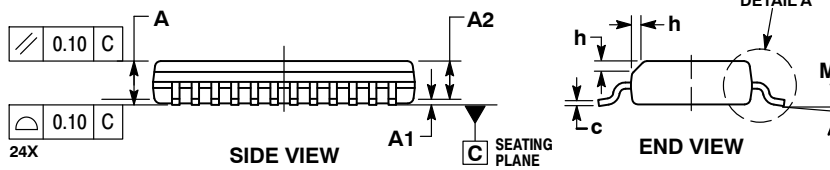
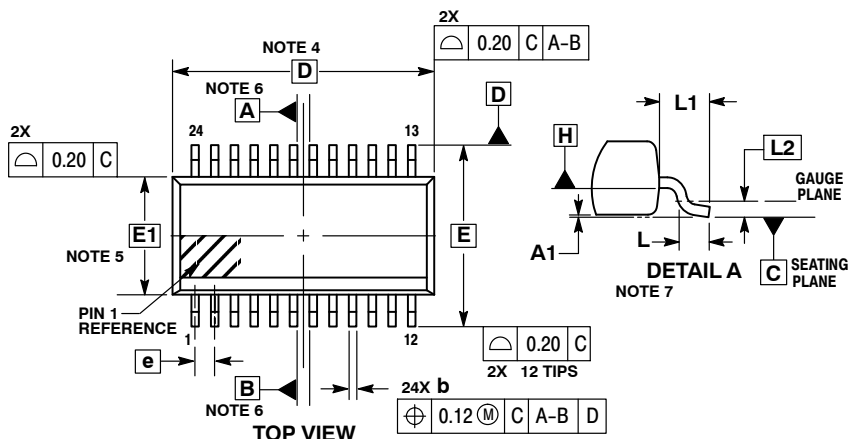
ON Semiconductor®



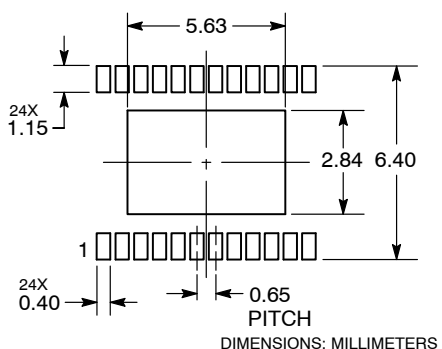
SCALE 1:1

SSOP24 NB EP
CASE 940AK
ISSUE O

DATE 24 APR 2012



RECOMMENDED SOLDERING FOOTPRINT



- NOTES:
1. DIMENSIONING AND TOLERANCING PER ASME Y14.5M, 1994.
 2. CONTROLLING DIMENSION: MILLIMETERS.
 3. DIMENSION b DOES NOT INCLUDE DAMBAR PROTRUSION. DAMBAR PROTRUSION SHALL BE 0.10 MAX. AT MMC. DAMBAR CANNOT BE LOCATED ON THE LOWER RADIUS OF THE FOOT. DIMENSION b APPLIES TO THE FLAT SECTION OF THE LEAD BETWEEN 0.10 TO 0.25 FROM THE LEAD TIP.
 4. DIMENSION D DOES NOT INCLUDE MOLD FLASH, PROTRUSIONS OR GATE BURRS. MOLD FLASH, PROTRUSIONS OR GATE BURRS SHALL NOT EXCEED 0.15 PER SIDE. DIMENSION D IS DETERMINED AT DATUM PLANE H.
 5. DIMENSION E1 DOES NOT INCLUDE INTERLEAD FLASH OR PROTRUSION. INTERLEAD FLASH OR PROTRUSION SHALL NOT EXCEED 0.25 PER SIDE. DIMENSION E1 IS DETERMINED AT DATUM PLANE H.
 6. DATUMS A AND B ARE DETERMINED AT DATUM PLANE H.
 7. A1 IS DEFINED AS THE VERTICAL DISTANCE FROM THE SEATING PLANE TO THE LOWEST POINT ON THE PACKAGE BODY.
 8. CONTOURS OF THE THERMAL PAD ARE UNCONTROLLED WITHIN THE REGION DEFINED BY DIMENSIONS D2 AND E2.

MILLIMETERS		
DIM	MIN	MAX
A	---	1.70
A1	0.00	0.10
A2	1.10	1.65
b	0.19	0.30
c	0.09	0.20
D	8.64 BSC	
D2	5.28	5.58
E	6.00 BSC	
E1	3.90 BSC	
E2	2.44	2.64
e	0.65 BSC	
h	0.25	0.50
L	0.40	0.85
L1	1.00 REF	
L2	0.25 BSC	
M	0°	8°

GENERIC MARKING DIAGRAM*



- XXXX = Specific Device Code
 - A = Assembly Location
 - WL = Wafer Lot
 - YY = Year
 - WW = Work Week
 - G = Pb-Free Package
- (Note: Microdot may be in either location)

*This information is generic. Please refer to device data sheet for actual part marking. Pb-Free indicator, "G" or microdot "•", may or may not be present. Some products may not follow the Generic Marking.

DOCUMENT NUMBER:	98AON79998E	Electronic versions are uncontrolled except when accessed directly from the Document Repository. Printed versions are uncontrolled except when stamped "CONTROLLED COPY" in red.
DESCRIPTION:	SSOP24 NB EP	PAGE 1 OF 1

ON Semiconductor and ON are trademarks of Semiconductor Components Industries, LLC dba ON Semiconductor or its subsidiaries in the United States and/or other countries. ON Semiconductor reserves the right to make changes without further notice to any products herein. ON Semiconductor makes no warranty, representation or guarantee regarding the suitability of its products for any particular purpose, nor does ON Semiconductor assume any liability arising out of the application or use of any product or circuit, and specifically disclaims any and all liability, including without limitation special, consequential or incidental damages. ON Semiconductor does not convey any license under its patent rights nor the rights of others.